Special Issue

Recent Progress in RF MEMS Devices and Applications

Message from the Guest Editor

Since the 1990s, researchers have been exploring the potential of MEMS technology to enhance radiofrequency (RF) performance. RF MEMS technology has drawn significant attention due to its unique performance, including miniaturization, low power consumption, high linearity, high durability, and lower manufacturing costs. These advantages make RF MEMS technology play an increasingly important role in modern wireless communications, the Internet of Things (IoT), smart systems, wearable technology, and biomedical devices. This Special Issue seeks to showcase research papers and comprehensive reviews reporting novel materials, designs, fabrication techniques, applications, packaging methods, and the reliability of RF MEMS. We look forward to receiving your submissions!

Guest Editor

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